

# LXA06T600, LXA06B600

## Qspeed™ Family

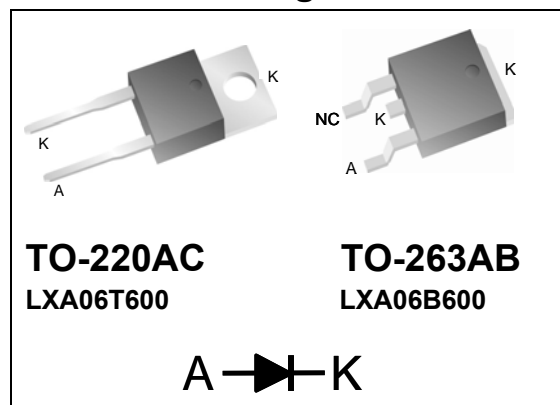


600 V, 6 A X-Series PFC Diode

### Product Summary

$I_{F(AVG)}$	6	A
$V_{RRM}$	600	V
$Q_{RR}$ (Typ at 125 °C)	71	nC
$I_{RRM}$ (Typ at 125 °C)	3.1	A
Softness $t_b/t_a$ (Typ at 125 °C)	0.7	

### Pin Assignment



### RoHS Compliant

Package uses Lead-free plating and Green mold compound.  
Halogen free per IEC 61249-2-21.

### General Description

This device has the lowest  $Q_{RR}$  of any 600V Silicon diode. Its recovery characteristics increase efficiency, reduce EMI and eliminate snubbers.

### Applications

- Power Factor Correction (PFC) Boost Diode
- Motor drive circuits
- DC-AC Inverters

### Features

- Low  $Q_{RR}$ , Low  $I_{RRM}$ , Low  $t_{RR}$
- High  $di_f/dt$  capable (1000A/ $\mu$ s)
- Soft recovery

### Benefits

- Increases efficiency
  - Eliminates need for snubber circuits
  - Reduces EMI filter component size & count
- Enables extremely fast switching

### Absolute Maximum Ratings

Absolute maximum ratings are the values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Symbol	Parameter	Conditions	Rating	Units
$V_{RRM}$	Peak repetitive reverse voltage		600	V
$I_{F(AVG)}$	Average forward current	$T_J = 150\text{ °C}$ , $T_C = 121\text{ °C}$	6	A
$I_{FSM}$	Non-repetitive peak surge current	60 Hz, 1/2 cycle	50	A
$I_{FSM}$	Non-repetitive peak surge current	1/2 cycle of $t=28\ \mu$ s Sinusoid, $T_C=25\text{ °C}$	350	A
$T_{J(MAX)}$	Maximum junction temperature		150	°C
$T_{STG}$	Storage temperature		-55 to 150	°C
	Lead soldering temperature	Leads at 1.6 mm from case, 10 sec	300	°C
$P_D$	Power dissipation	$T_C = 25\text{ °C}$	62.5	W

### Thermal Resistance

Symbol	Resistance from:	Conditions	Rating	Units
$R_{\theta JA}$	Junction to ambient	TO-220 (Only)	62	°C/W
$R_{\theta JC}$	Junction to case		2.0	°C/W

**Electrical Specifications at T<sub>J</sub> = 25 °C (unless otherwise specified)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units	
<b>DC Characteristics</b>							
I <sub>R</sub>	Reverse current	V <sub>R</sub> = 600V, T <sub>J</sub> = 25 °C	-	-	250	μA	
		V <sub>R</sub> = 600V, T <sub>J</sub> = 125 °C	-	0.7	-	mA	
V <sub>F</sub>	Forward voltage	I <sub>F</sub> = 6A, T <sub>J</sub> = 25 °C	-	2.27	2.94	V	
		I <sub>F</sub> = 6A, T <sub>J</sub> = 150 °C	-	2.0	-	V	
C <sub>J</sub>	Junction capacitance	V <sub>R</sub> = 10V, 1 MHz	-	30	-	pF	
<b>Dynamic Characteristics</b>							
t <sub>RR</sub>	Reverse recovery time	di/dt = 200 A/μs V <sub>R</sub> = 400 V, I <sub>F</sub> = 6 A	T <sub>J</sub> = 25 °C	-	23	-	ns
			T <sub>J</sub> = 125 °C	-	32	-	ns
Q <sub>RR</sub>	Reverse recovery charge	di/dt = 200 A/μs V <sub>R</sub> = 400 V, I <sub>F</sub> = 6 A	T <sub>J</sub> = 25 °C	-	30	47	nC
			T <sub>J</sub> = 125 °C	-	71	-	nC
I <sub>RRM</sub>	Maximum reverse recovery current	di/dt = 200 A/μs V <sub>R</sub> = 400 V, I <sub>F</sub> = 6 A	T <sub>J</sub> = 25 °C	-	2.0	2.5	A
			T <sub>J</sub> = 125 °C	-	3.1	-	A
S	Softness factor = $\frac{t_b}{t_a}$	di/dt = 200 A/μs V <sub>R</sub> = 400 V, I <sub>F</sub> = 6 A	T <sub>J</sub> = 25 °C	-	0.8	-	
			T <sub>J</sub> = 125 °C	-	0.7	-	

**Note to component engineers:** X-Series diodes employ Schottky technologies in their design and construction. Therefore, Component Engineers should plan their test setups to be similar to those for traditional Schottky test setups. (For additional details, see Application Note AN-300.)

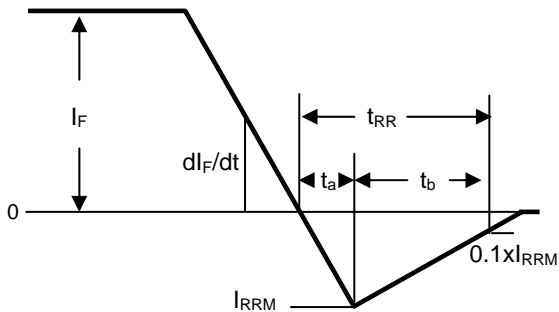


Figure 1. Reverse Recovery Definitions

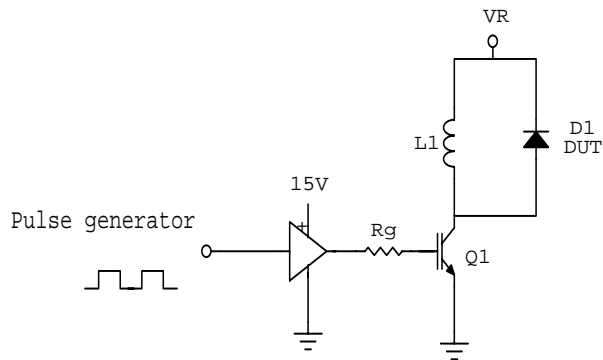


Figure 2. Reverse Recovery Test Circuit

Electrical Specifications at  $T_J = 25\text{ }^\circ\text{C}$  (unless otherwise specified)

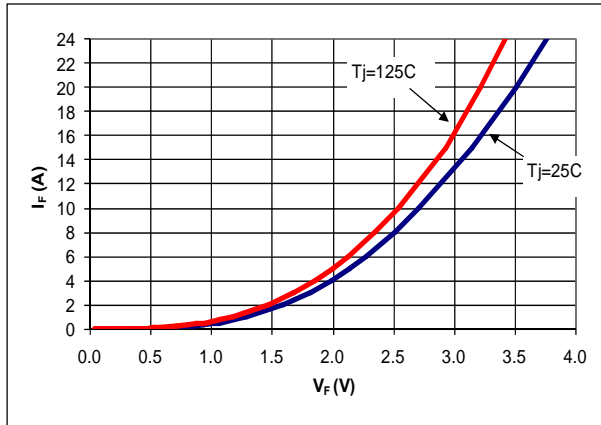


Figure 3. Typical  $I_F$  vs  $V_F$

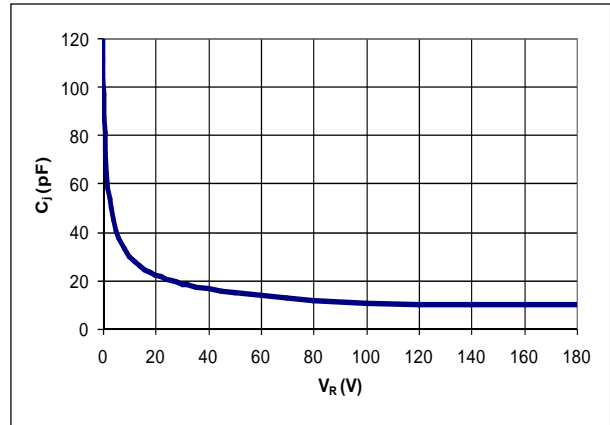


Figure 4. Typical  $C_i$  vs  $V_R$

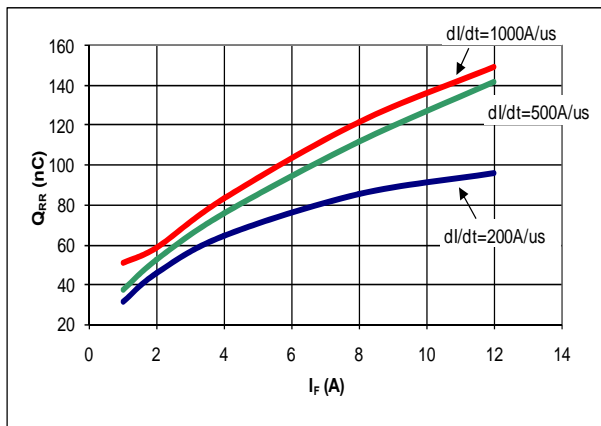


Figure 5. Typical  $Q_{RR}$  vs  $I_F$  at  $T_J = 125\text{ }^\circ\text{C}$

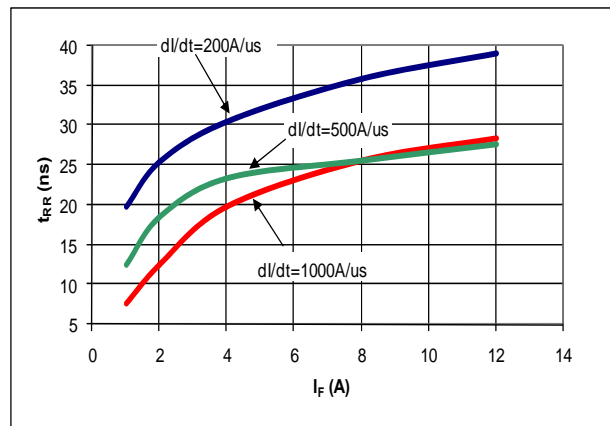


Figure 6. Typical  $t_{RR}$  vs  $I_F$  at  $T_J = 125\text{ }^\circ\text{C}$

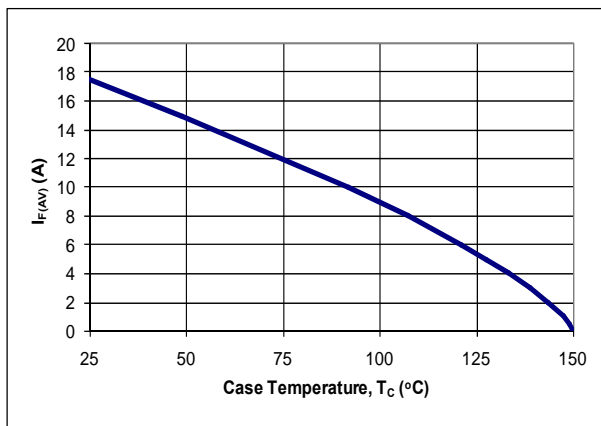


Figure 7. DC Current Derating Cur

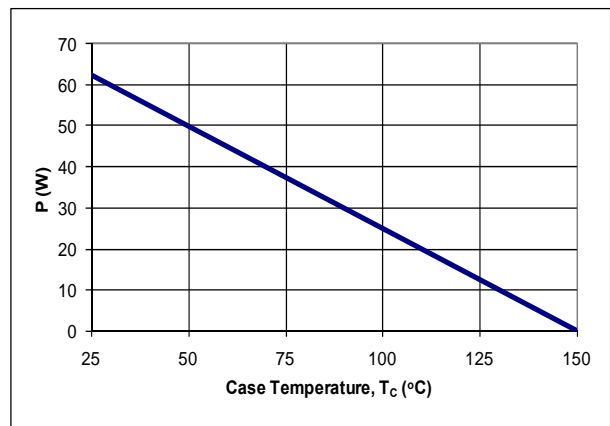


Figure 8. Power Derating Curve

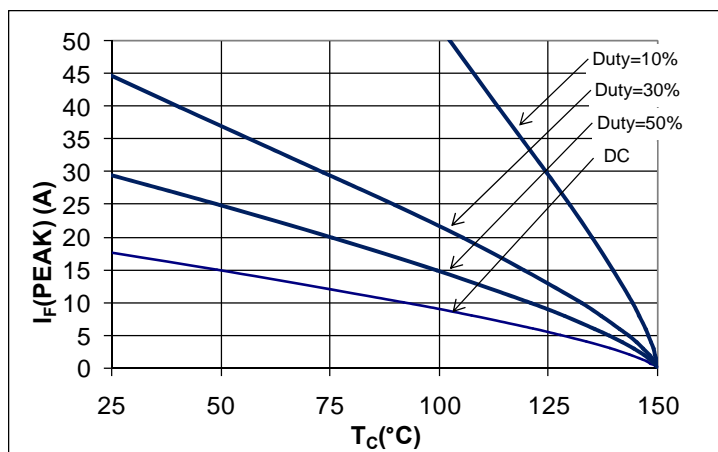


Figure 9. I<sub>f</sub>(PEAK) vs T<sub>c</sub>, f=70 kHz

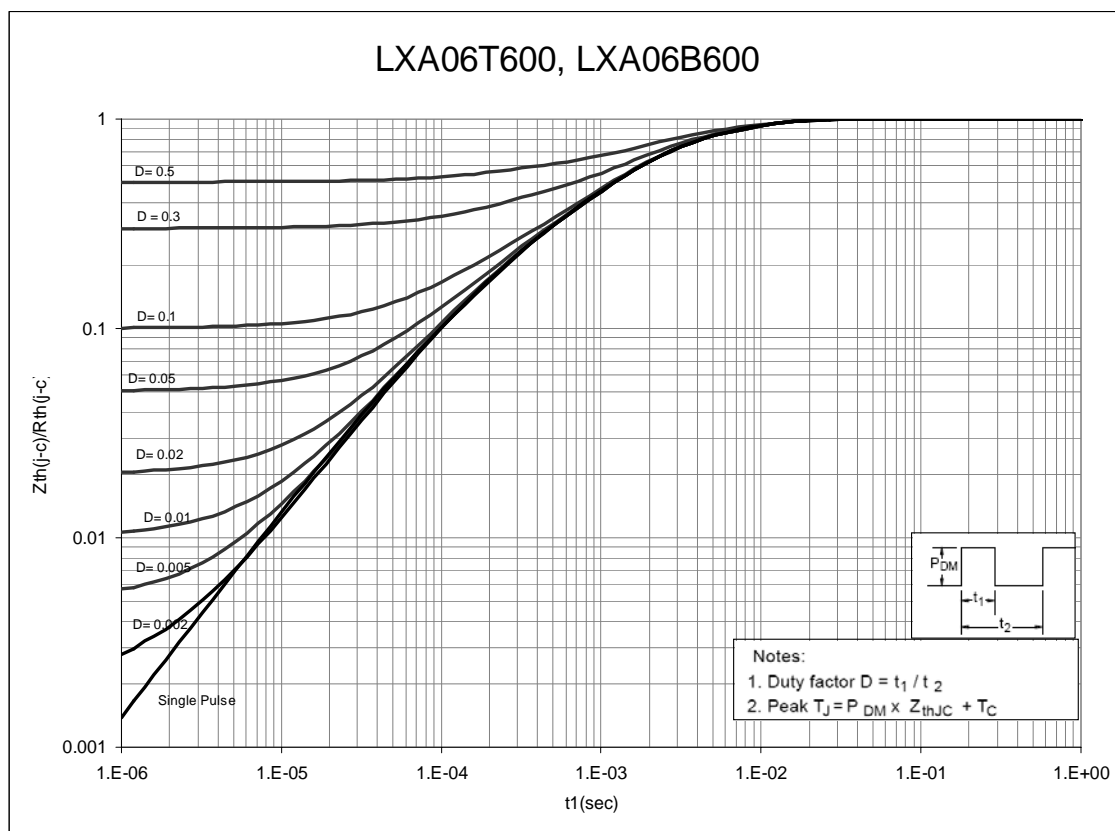
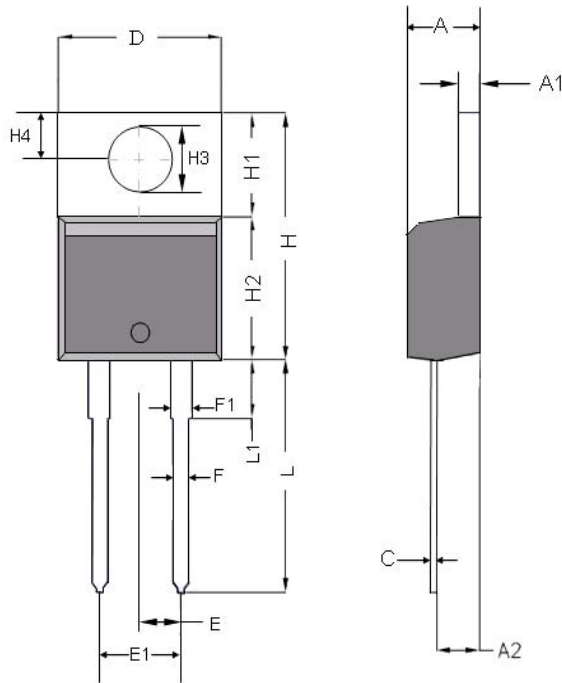


Figure 10. Normalized Maximum Transient Thermal Impedance

## Dimensional Outline Drawings

### TO-220AC

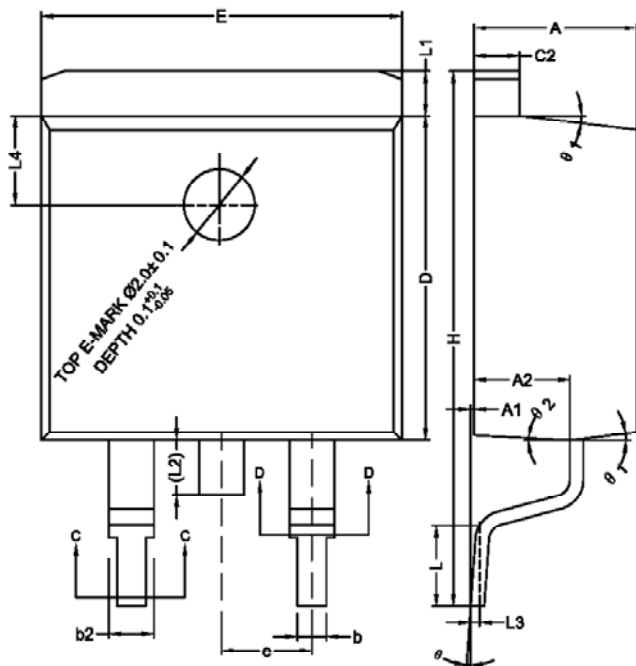


Dim	Millimeters	
	MIN	MAX
A	4.32	4.70
A1	1.14	1.40
A2	2.03	2.79
C	0.34	0.610
D	9.65	10.67
E	2.49	2.59
E1	4.98	5.18
F	0.508	1.016
F1	1.14	1.78
H	14.71	16.51
H1	5.84	6.55
H2	8.51	9.25
H3	3.53	3.96
H4	2.54	3.05
L	12.70	14.22
L1	-	6.35

Mechanical Mounting Method	Maximum Torque / Pressure specification
Screw through hole in package tab	1 Newton Meter (nm) or 8.8 inch-pounds (lb-in)
Clamp against package body	12.3 kilogram-force per square centimeter (kgf/cm <sup>2</sup> ) or 175 lbf/in <sup>2</sup>

**Soldering time and temperature:** This product has been designed for use with high-temperature, lead-free solder. The component leads can be subjected to a maximum temperature of 300 °C, for up to 10 seconds. See Application Note AN-303, for more details.

## TO-263AB



Dim	Millimeters	
	MIN	MAX
A	4.40	4.70
A1	0.00	0.25
A2	2.59	2.79
b	0.77	0.90
b2	1.23	1.36
c2	1.22	1.32
D	9.05	9.25
E	10.06	10.26
e	2.54 BSC	2.54 BSC
H	14.70	15.50
L	2.00	2.60
L1	1.17	1.40
L2	–	1.75
L3	0.25 BSC	0.25 BSC
L4	2.00 BSC	2.00 BSC
Θ	0°	8°
Θ1	5°	9°
Θ2	1°	5°

## Ordering Information

Part Number	Package	Packing
LXA06T600	TO-220AC	50 units/tube
LXA06B600	TO-263AB	800 units/reel

The information contained in this document is subject to change without notice.

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<b>Revision</b>	<b>Notes</b>	<b>Date</b>
1.6	Released by Qspeed	05/10
1.7	Converted to Power Integrations Document	01/11

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## Power Integrations Worldwide Sales Support Locations

### WORLD HEADQUARTERS

5245 Hellyer Avenue  
San Jose, CA 95138, USA.  
Main: +1-408-414-9200  
Customer Service:  
Phone: +1-408-414-9665  
Fax: +1-408-414-9765  
*e-mail:*  
[usasales@powerint.com](mailto:usasales@powerint.com)

### GERMANY

Rueckertstrasse 3  
D-80336, Munich  
Germany  
Phone: +49-89-5527-3911  
Fax: +49-89-5527-3920  
*e-mail:*  
[eurosales@powerint.com](mailto:eurosales@powerint.com)

### JAPAN

Kosei Dai-3 Building  
2-12-11, Shin-Yokohama,  
Kohoku-ku, Yokohama-shi,  
Kanagawa 222-0033  
Japan  
Phone: +81-45-471-1021  
Fax: +81-45-471-3717  
*e-mail:* [japansales@powerint.com](mailto:japansales@powerint.com)

### TAIWAN

5F, No. 318, Nei Hu Rd., Sec. 1  
Nei Hu District  
Taipei 114, Taiwan R.O.C.  
Phone: +886-2-2659-4570  
Fax: +886-2-2659-4550  
*e-mail:*  
[taiwansales@powerint.com](mailto:taiwansales@powerint.com)

### CHINA (SHANGHAI)

Rm 1601/1610, Tower 1  
Kerry Everbright City  
No. 218 Tianmu Road West  
Shanghai, P.R.C. 200070  
Phone: +86-021-6354-6323  
Fax: +86-021-6354-6325  
*e-mail:*  
[chinasales@powerint.com](mailto:chinasales@powerint.com)

### INDIA

#1, 14<sup>th</sup> Main Road  
Vasanthanagar  
Bangalore-560052  
India  
Phone: +91-80-4113-8020  
Fax: +91-80-4113-8023  
*e-mail:*  
[indiasales@powerint.com](mailto:indiasales@powerint.com)

### KOREA

RM 602, 6FL  
Korea City Air Terminal B/D, 159-6  
Samsung-Dong, Kangnam-Gu,  
Seoul, 135-728  
Korea  
Phone: +82-2-2016-6610  
Fax: +82-2-2016-6630  
*e-mail:* [koreasales@powerint.com](mailto:koreasales@powerint.com)

### EUROPE HQ

1st Floor, St. James's House  
East Street, Farnham  
Surrey GU9 7TJ  
United Kingdom  
Phone: +44 (0) 1252-730-141  
Fax: +44 (0) 1252-727-689  
*e-mail:*  
[eurosales@powerint.com](mailto:eurosales@powerint.com)

### CHINA (SHENZHEN)

Rm A, B & C 4<sup>th</sup> Floor, Block C,  
Electronics Science and  
Technology Building  
2070 Shennan Zhong Road  
Shenzhen, Guangdong,  
P.R.C. 518031  
Phone: +86-755-8379-3243  
Fax: +86-755-8379-5828  
*e-mail:*  
[chinasales@powerint.com](mailto:chinasales@powerint.com)

### ITALY

Via De Amicis 2  
20091 Bresso MI  
Italy  
Phone: +39-028-928-6000  
Fax: +39-028-928-6009  
*e-mail:*  
[eurosales@powerint.com](mailto:eurosales@powerint.com)

### SINGAPORE

51 Newton Road,  
#19-01/05 Goldhill Plaza  
Singapore, 308900  
Phone: +65-6358-2160  
Fax: +65-6358-2015  
*e-mail:*  
[singaporesales@powerint.com](mailto:singaporesales@powerint.com)

### APPLICATIONS HOTLINE

World Wide +1-408-414-9660

### APPLICATIONS FAX

World Wide +1-408-414-9760